



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01373		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/3/2017	2:20:06 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01373		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/3/2017	2:20:07 PM	TEXAS INSTRUMENTS

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